

Status of DMAPS (WP5) Activities

S. Grinstein (IFAE-Barcelona) and F. Hüggling, N. Wermes (Bonn)

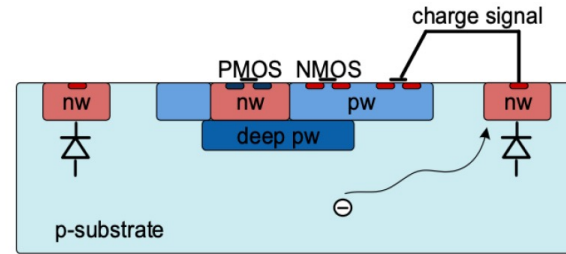
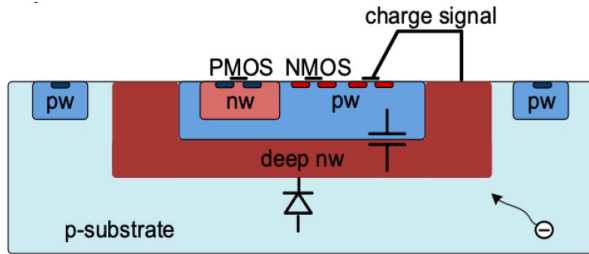
2nd Annual Meeting Valencia – 26 Apr 2023
<https://indico.cern.ch/event/1191719/>



This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement No 101004761.

- 7 projects are (partially, not exclusively) supported by the AIDAInnova framework using 4 different processes provided by 2 foundries: **LFoundry** (Wuxi Xichanweixin Semiconductor) and **TowerJazz** → Tower Semiconductor (Intel as of 2022)
- All developments have samples, characterisation in full swing

large electrode (radhard)



small electrode (high granularity)

Submission	Process	Availability	Target	Comments	Contact Institute	Task Contact
TJ-MALTA 2 /3	TowerJazz 180 nm	Beginning 2021 MPW Q1 2022	High-gran./ Rad. hard Task 5.2/5.3	LHC	CERN	Carlos Solans Sanchez
TJ-Monopix 2 /3 (OBELIX)	TowerJazz 180 nm	Spring 2021 Initiating design	High-granularity Task 5.2	Belle II	Bonn	Jochen Dingfelder
TJ 65	TowerJazz 65 nm	September 2021	High-granularity Task 5.2	Generic R&D / ALICE	IPHC	Jerome Baudot
ARCADIA	LFoundry 110 nm	Summer 2021	High-granularity Task 5.2	Demonstrator chip	INFN	Manuel Rolo
LF-Monopix 2	LFoundry 150 nm	Beginning 2021	Radiation hard Task 5.3	High granularity foreseen	Bonn/CPPM	Marlon Barbero
RD50-MPW 3 /4	LFoundry 150 nm	Spring 2022	High-granularity/ Radiation hard Task 5.3	R&D	Liverpool	Eva Vilella
MiniCactus	LFoundry 150 nm	Beginning 2021	Radiation hard Task 5.3	Timing R&D	IRFU	Philippe Schwemling

April 2021

Tasks	Description	Year 1												Year 2												Year 3												Year 4																													
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48	49	50																
WP5: Depleted Monolithic Active Pixel Sensors																																																																			
5.1	Coordination and Communication																																																																		
5.2	Development of high granularity DMAPS													M											D											M											D																				
5.3	Development of radiation hard DMAPS																							M											D											M											D										

WP5 Deliverables consist of reports, which are the responsibility of the institutes in the last column.

Due Jan 2023, results available, report written

Deliverables related to WP5		March 2023 ✓	
D5.1: Report on performance of high granularity DMAPS Version 1 <i>Report on performance of high granularity monolithic pixel sensor 1 (task 5.2)</i>	22		CNRS-IPHC
D5.2: Report on performance of high granularity DMAPS Version 2 <i>Report on performance of high granularity monolithic pixel sensor 2 (task 5.2)</i>	44		INFN
D5.3: Report on performance of radiation-hard DMAPS <i>Report on performance of structures and the radiation hard monolithic pixel 1 (task 5.3)</i>	36		Bonn
D5.4: Report of beam tests of irradiated radiation-hard DMAPS <i>Report of beam tests of radiation-hard devices after high irradiation (task 5.3)</i>	46		CERN

See also: <https://aidainnova.web.cern.ch/wp5>

April 2021

		Year 1												Year 2												Year 3												Year 4																										
Tasks	Description	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48	49	50													
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Milestones have short associated reports and are within the responsibility of the institutes in the last column.

April 2022 ✓

MS5.1	High granularity prototype fabrication 1	5.2	M12	Devices available	CNRS-IPHC
MS5.2	High granularity prototype fabrication 2	5.2	M36	Devices available	INFN
MS5.3	Radiation hard prototype fabrication	5.3	M23	Devices available	Bonn
MS5.4	Test beam of the radiation hard monolithic pixel 1	5.3	M42	Test beam with prototypes measured	CERN

Rad hard prototypes exist, characterization is far advanced, due: end of Feb 2023 => report written

See also: <https://aidainnova.web.cern.ch/wp5>

TJ-MALTA

- JINST 2021 <https://doi.org/10.5281/zenodo.6951327>
- TWEPP 2021 <https://doi.org/10.1088/1748-0221/17/04/C04034>
- IEEE TNS 2022 <https://doi.org/10.1109/TNS.2022.3170729>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167390>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167226>
- NIM A 2023 <https://doi.org/10.1016/j.nima.2022.167809>

TJ-Monopix

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167189>
- arXiv 2023 <https://doi.org/10.48550/arXiv.2301.13638>

LF-Monopix

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167224>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.166747>

CACTUS

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167022>

TJ 65nm

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167213>

RD50-MPW

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.166826>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167020>
- JINST 2023 <https://doi.org/10.1088/1748-0221/17/12/C12017>

15 publications
so far

WP5 meetings at:
<https://indico.cern.ch/category/13503/>

- Next slides are a brief summary of recent achievements as presented during the Annual meeting
- See details in WP5 session on Apr. 25:
 - <https://indico.cern.ch/event/1191719/sessions/454935/#20230425>

15:00	Recent Results on irradiated LF Monopix 2 https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Lars Philip Schall	15:00 - 15:20
	Results on TJ Malta https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Marcos Vazquez Nunez	15:20 - 15:40
	Performance of unirradiated TJ-Monopix 2 https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Christian Bospin	15:40 - 16:00
16:00	Coffee break https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7		16:15 - 16:30
	Obelix for Belle II https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Maximilian Babeluk	16:30 - 16:50
17:00	Sub 100 ps time measurements with non-amplified DMAPS https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Jean-Pierre Meyer et al.	16:50 - 17:10
	Development and evaluation of the RD50-MPW chips in the LFoundry 150 nm HV-CMOS process Ricardo Marco Hernandez et al.		
	DMAPS activities at PSI https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Stephan Tobias Burkhalter	17:30 - 17:50
	DMAPS developments in TPSCo 65nm https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Jerome Baudot	17:50 - 18:10
18:00	Ring oscillator tests in TJ/TPSCo 65 https://cern.zoom.us/j/61522320218?pwd=ZGpWT3F6YXk0ZmRYT1dFTSswRkpmQT09 , Aula 2.7	Marlon B. Barbero	18:10 - 18:30

Tower 180 nm
TJ-MALTA-2&3
TJ-Monopix-2

Goal: large (1x2 cm² (Malta2) -> 3x2 cm² (Malta3)) radhard sensor/chip w/ small electrode and high granularity, HL-LHC-layer-5 compatible with low power **asynchronous** readout architecture. **Sensor&FE same as TJ-Monopix.**

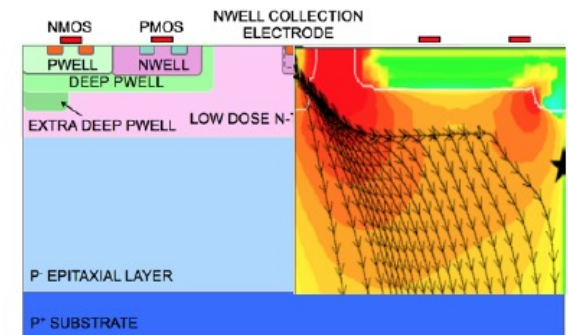
CERN and others (Bonn, CPPM, Oxford ...)
- 180 nm technology -

- main objective of TJ-MALTA2:

- make design radhard ($> 1e15$ neq/cm²):
 - i. shape charge collection geometry
 - ii. optimize FE against RTS noise
 - iii. use high resistive Cz-Si substrate (100 μ m) rather than epi-Si (25 μ m).
- improve asynchronous readout

- objective TJ-MALTA3:

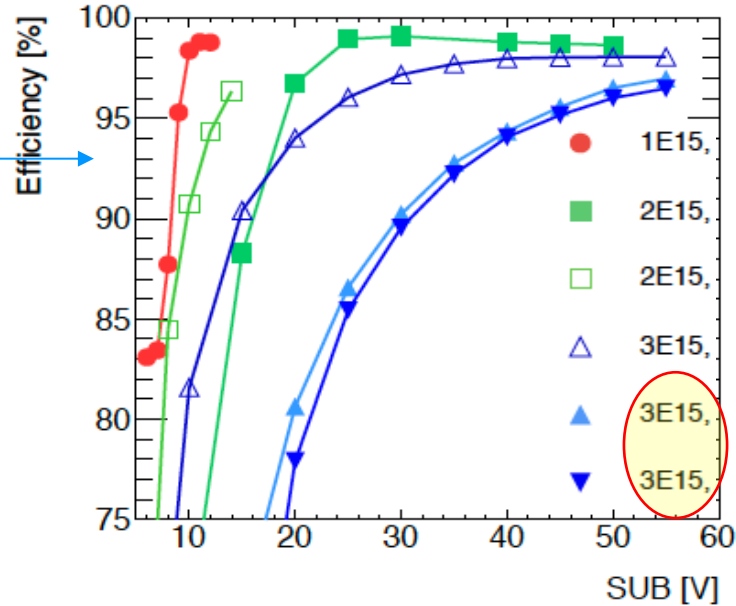
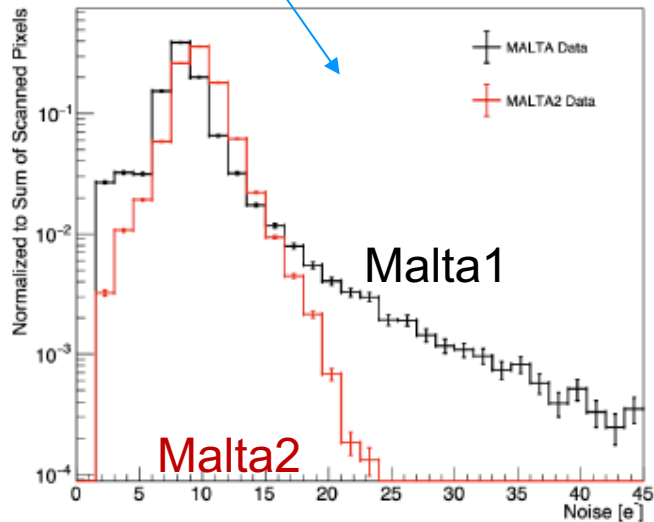
- exploit full reticle size: 3x2 cm²
- improve on remaining MALTA2 issues
- add 1.28 GHz local clock
- target: mini-MALTA MPW in Q2 2023



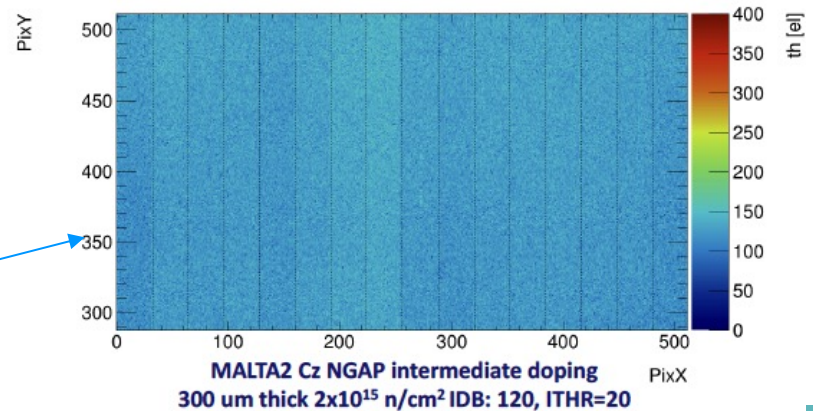
C. Solans. L. Flores et al.

Goals of MALTA2 achieved:

- radhard to $>1E15$ neq/cm²
- @ $3E15$ neq/cm² $> 95\%$ in 25ns
- RTS noise mitigated



- excellent matrix homogeneity



C. Solans. L. Flores et al.

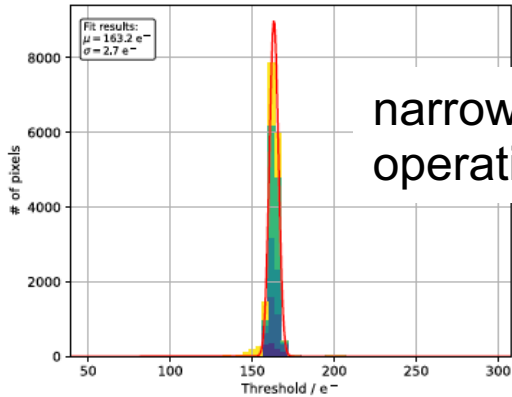
Goal: mature large ($2 \times 2 \text{ cm}^2$) high granularity (small electrode) fully functional, HL-LHC compatible (5th layer) DMAPS sensor with column drain readout, w/ low noise and low power consumption

	TJ-Monopix1	TJ-Monopix2
Chip Size	1x2 cm ² (224x448 pix)	2x2 cm ² (512x512 pix)
Pixel size	36 × 40 μm ²	33.04 × 33.04 μm ²
Total matrix power	130 mW/cm ²	170 mW/cm ²
Noise	≅ 11 e ⁻	< 8 e ⁻ (improved FE)
LE/TE time stamp	6-bit	7-bit
Threshold Dispersion	≅ 30 e ⁻ rms	< 10 e ⁻ rms (improved FE + tuning)
Minimum threshold	≅ 300 - 400 e ⁻	< 200 e ⁻
In-time threshold	≅ 350 - 450 e ⁻	< 250 - 300 e ⁻
Efficiency at 10 ¹⁵ n _{eq} /cm ² , 30 μm epi	≅ 87 %	> 97 %
Efficiency at 10 ¹⁵ n _{eq} /cm ² , Cz	≅ 98.6 %	> 99 %

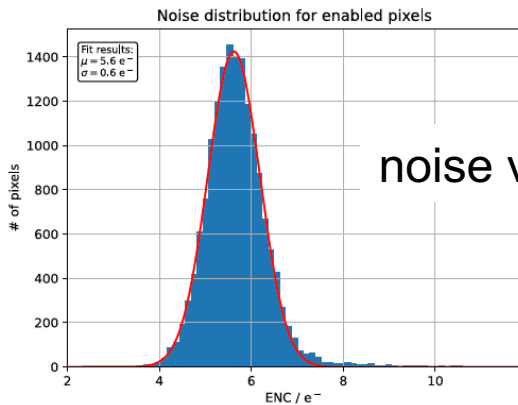
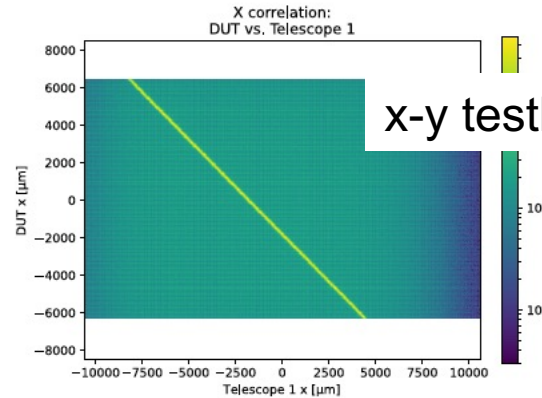
- Clear improvements wrt TJ-M1 before and after irradiation

Bonn, CERN, CPPM, IRFU
- 180 nm technology -

- sensor and chip working
- assembly problems (wire bonding sensibility) reduce yield, is now manageable, but still problematic
- a temporary major problem at 5 MHz BC-ID clock interfering now understood and circumvented
- characterisation finally in full swing
- baseline for Belle II VTX upgrade → Obelix chip:
 - Uses analog part from TJ Monopix 2
 - New digital periphery with several additional features

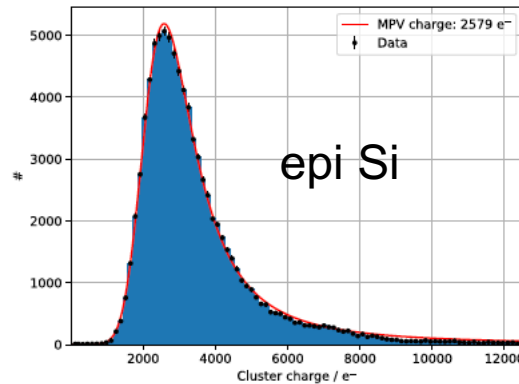


narrow (tuned)
operation threshold

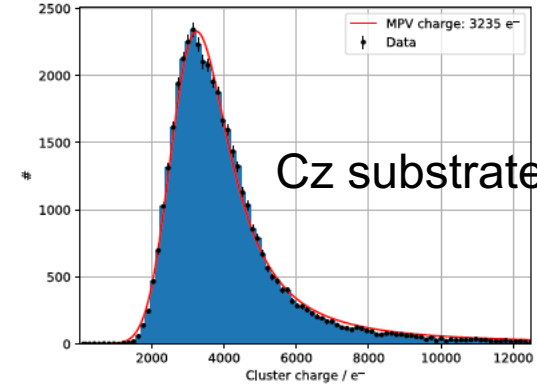


noise very low

Epi gap in n-layer: 2.5 ke- MPV



Cz gap in n-layer: 3.2 ke- MPV



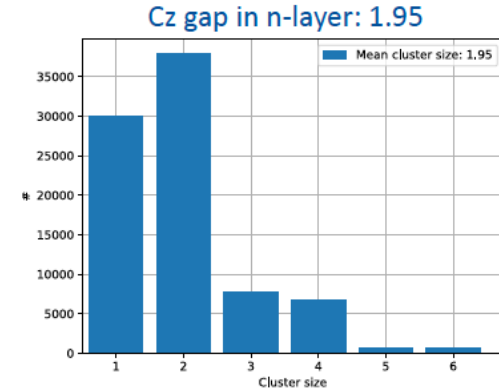
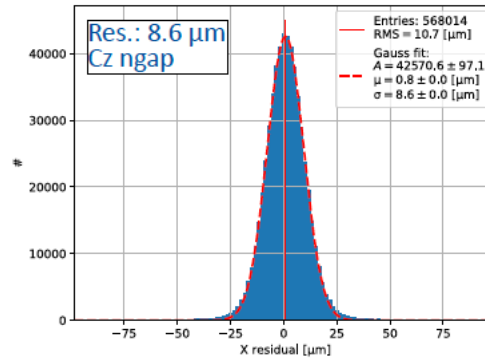
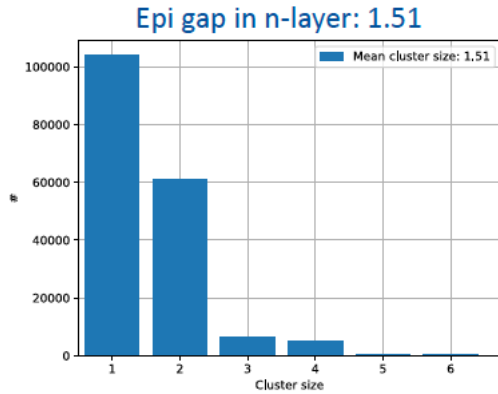
mip signals

(→ depletion profile still to be understood)

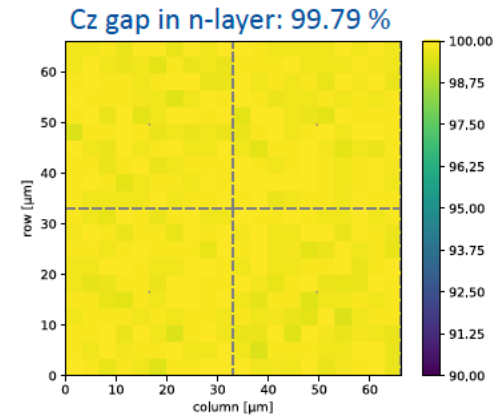
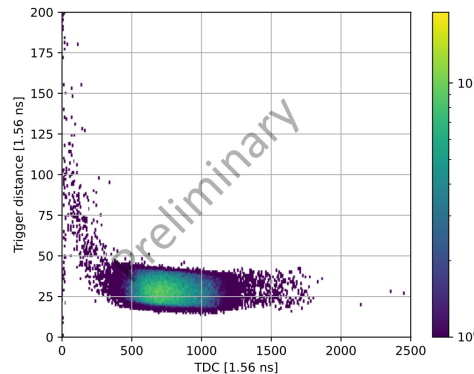
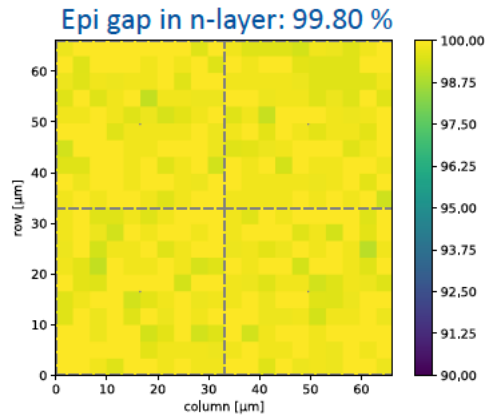
epi Si

resolution 8.6 μm

Cz substrate



very high efficiencies
(before irradiation)
irradiation planned Q1/Q2



Lars Schall, C. Besspin et al

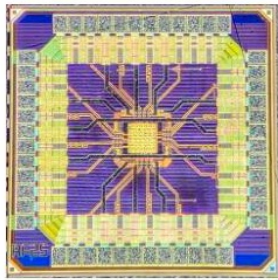
TPSCo 65 nm process of **Tower**
(new window of opportunity)

Tower 65nm

Goal: exploring the new technology (large collaboration effort, CERN + 24 institutions) including stitching, small electrode designs

1+2 submissions so far: MLR1 (2020), ER1 (2022) each containing several structures and designs

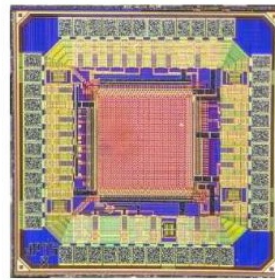
APTS Analogue Pixel Test Structure



Matrix: 6x6
Readout: analogue readout of 4x4
Pitch: 10,15,20,25 μm
Process: all 3 variants

1.5 mm

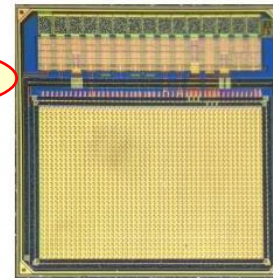
DPTS Digital Pixel Test Structure



Matrix: 32x32
Readout: async. digital with ToT
Pitch: 15 μm
Process: 1 variant (modified with gap process)

1.5 mm

CE-65 Circuit Exploratoire 65

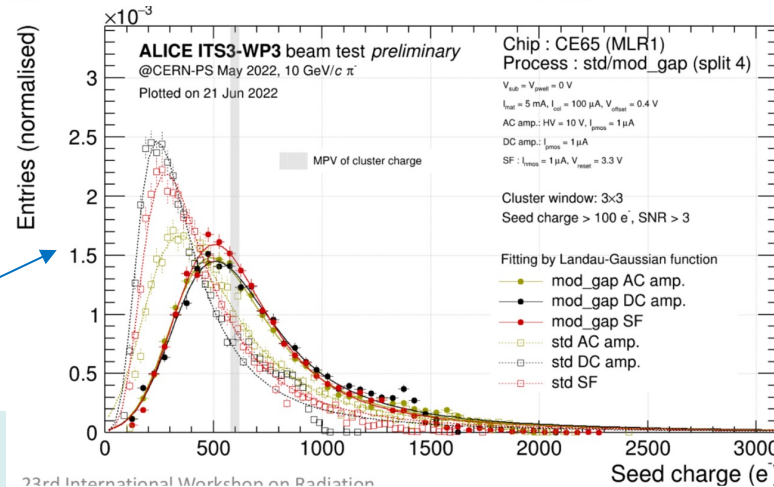


Matrix: 48x32
Readout: rolling shutter analog
Pitch: 15, 25 μm
Process: 1 variant (modified with gap process)

1.5 mm

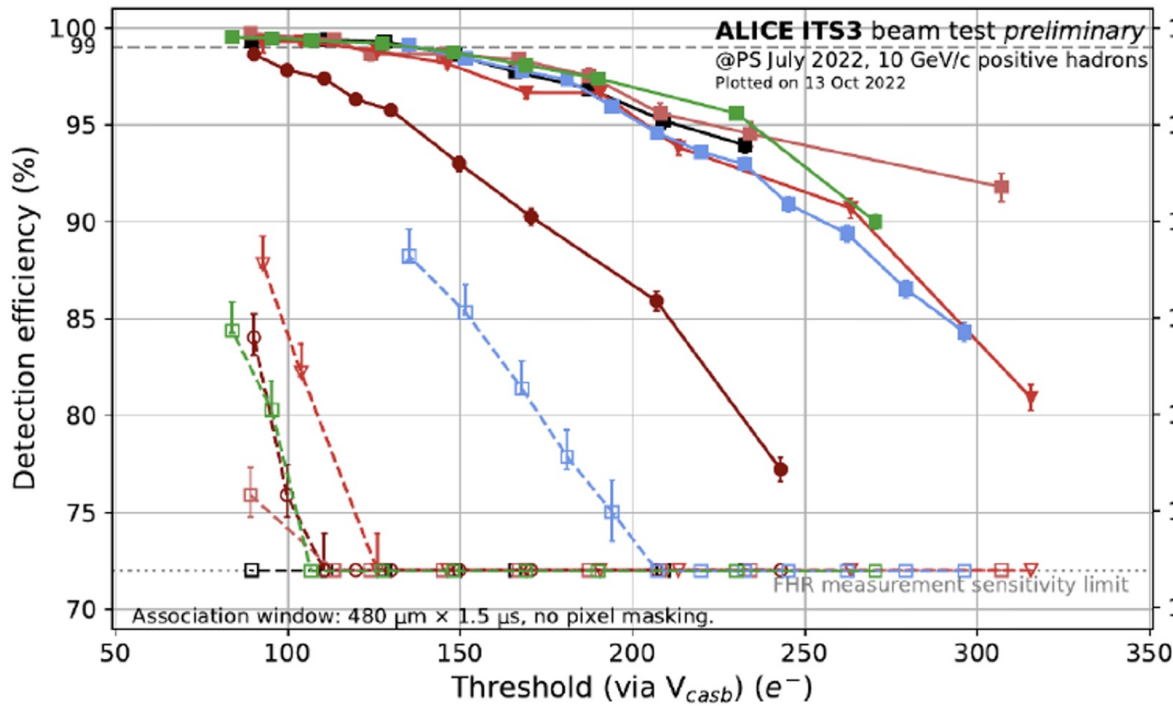
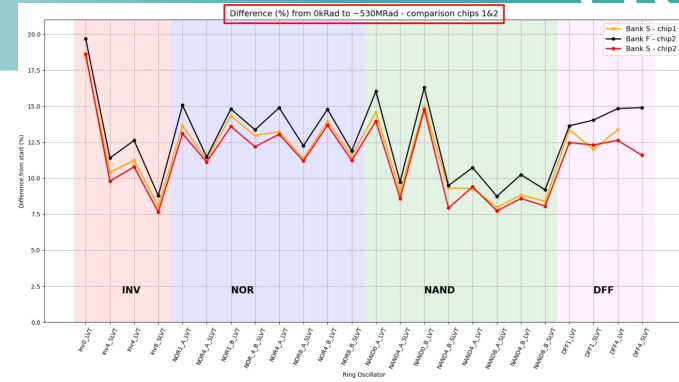
from MLR1

promising results from MLR1
leakage cur. ✓
Testbeam with DPTS (digital 15 μm) proved that process modification works



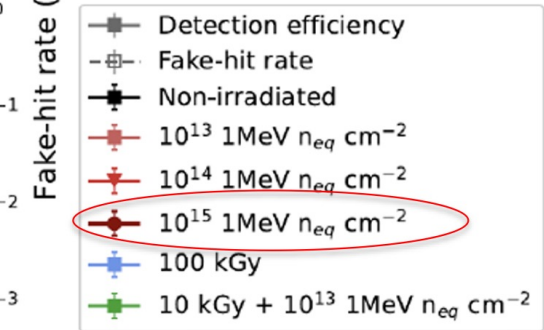
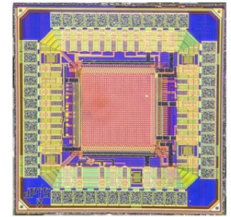
Promising radiation tolerance:

- DPTS (digital) with 15 μm pitch
- Beam test results
- also for digital cells as shown with TID measurements on ring oscillators



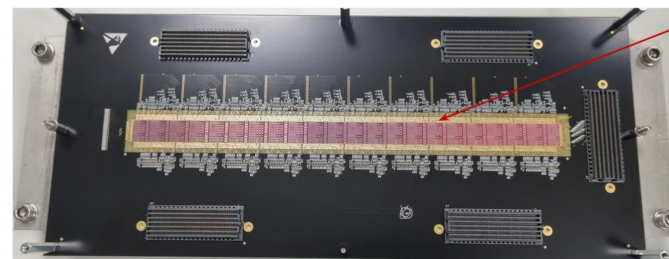
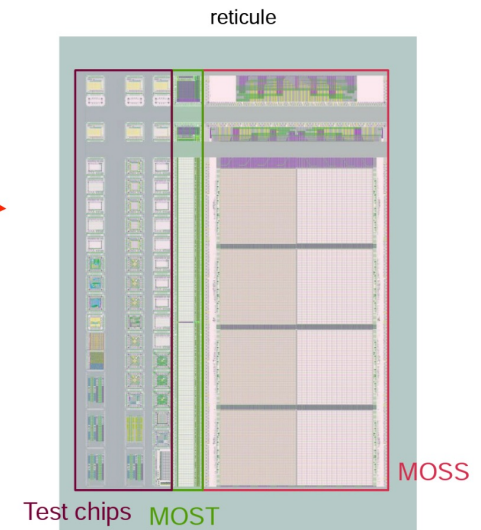
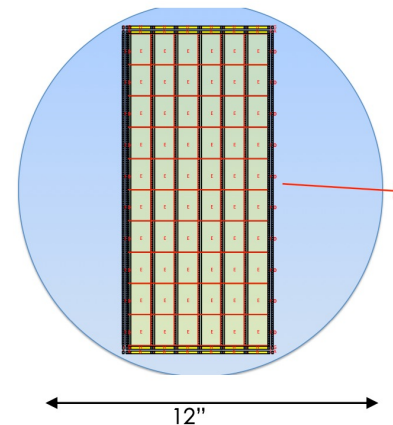
DPTS
 $V_{pwell} = V_{sub} = -2.4\text{V}$
 $I_{reset} = 35\text{pA}$
 $I_{bias} = 100\text{nA}$
 $I_{biasn} = 10\text{nA}$
 $I_{qb} = 50\text{nA}$
 $V_{casn} = \text{optimised}$
 $V_{casb} = \text{variable}$
 $T = 20^\circ\text{C}$

DPTS



2nd submission: Engineer Run 1 (ER1)

- Main goal = exercise stitching (in 1D) to assess yield
- Submission November 2022
- Back from fab April 2023
- 2 long (~26 cm) sensors
 - **MOSS**: priority-encoder readout (ALPIDE-like)
 - 1.4 cm wide
 - 18 & 22.5 μm pitch
 - **MOST**: low power asynchronous readout
 - 0.25 cm wide
- Many (51) **chipelets**
 - Pixel prototypes
 - SEU test chips
 - Functional blocks (PLL, serial links)
- New metal staks
- New methodology for submission
 - Digital-on-top



Test in preparation

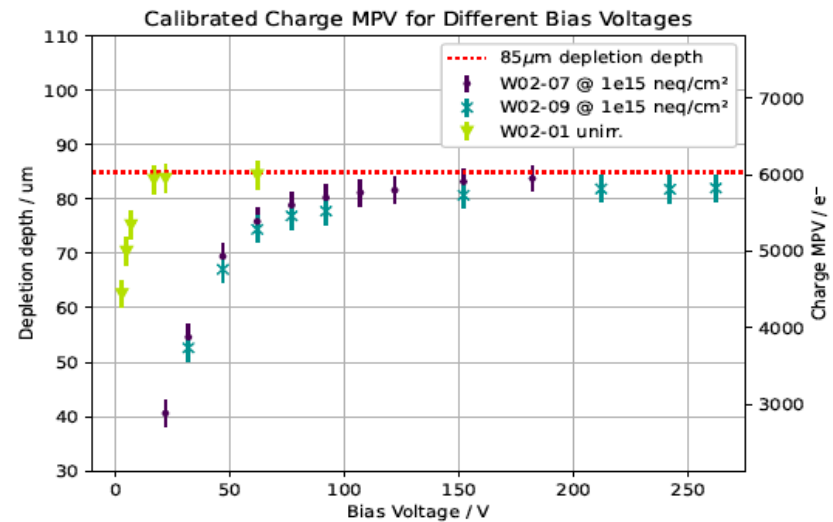
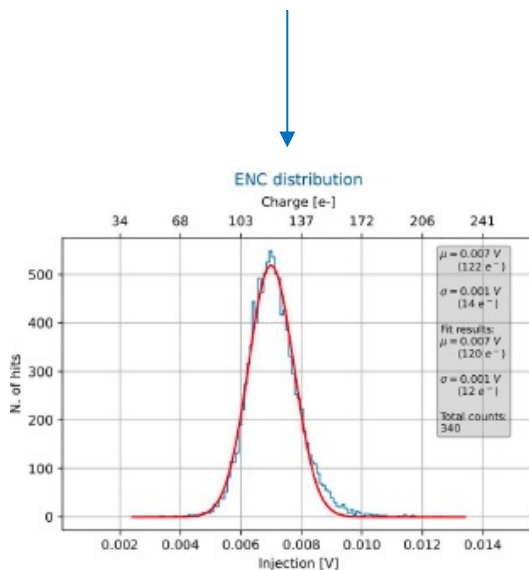
LFfoundry 150 nm

- LF-Monopix-2
- RD50 – MPW2/3
- CACTUS

Goal: mature large ($1 \times 2 \text{ cm}^2$) (very) radhard, large electrode fully functional, HL-LHC compatible (5th layer) DMAPS sensor with column drain readout

irradiated devices ($1 \times 10^{15} \text{ neq/cm}^2$ @ Bonn Cyclotron)

- no significant degradation at this level except for leakage current increase

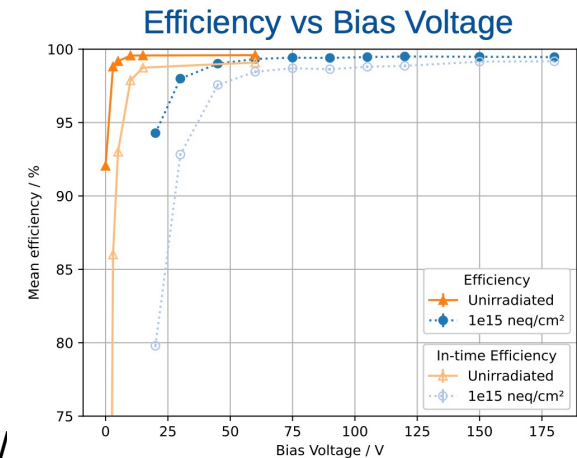
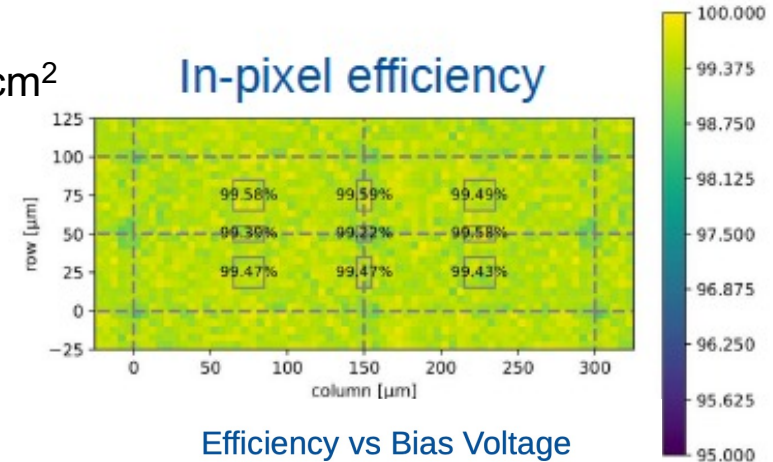
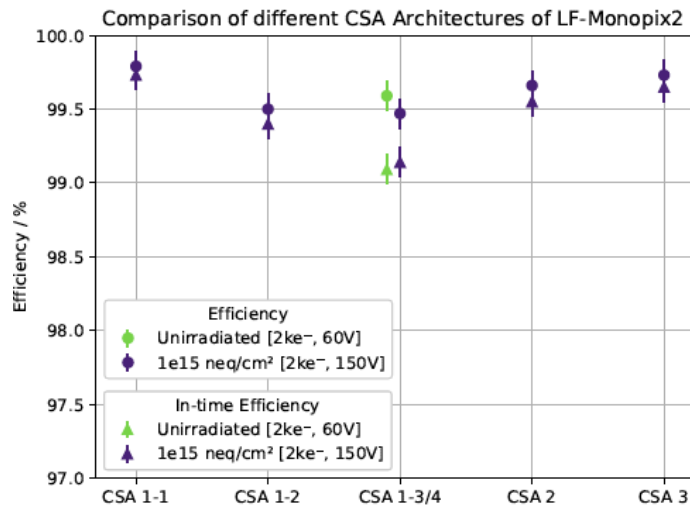


Lars Schall, C. Bospin, et al.

- fully depleted @ 100 V bias (15 V unir.)

Goal: mature large ($1 \times 2 \text{ cm}^2$) (very) radhard, large electrode fully functional, HL-LHC compatible (5th layer) DMAPS sensor with column drain readout

- intensive testbeam characterisation
- very high (>99%) efficiency (in-time) after $1 \text{e}15 \text{ neq/cm}^2$
- ~no efficiency degradation wrt unirradiated devices



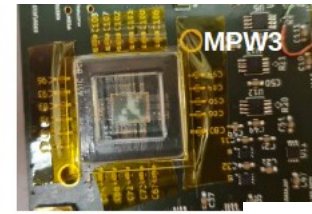
Lars Schall, C. Bepin, et al.

next: $1 \text{e}15 \text{ neq/cm}^2 \rightarrow 2 \text{e}15 \text{ neq/cm}^2$

Goal: series of MPWs (1 ... 4) to achieve very small pixels ($60 \times 60 \mu\text{m}^2$) radhard @ HL-LHC level 5th layer by large electrode design (all electronics inside deep well)

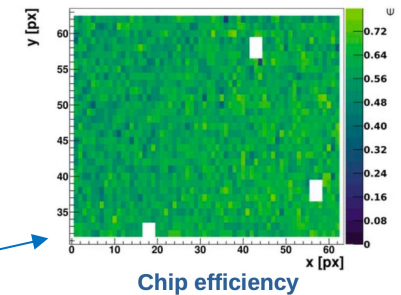
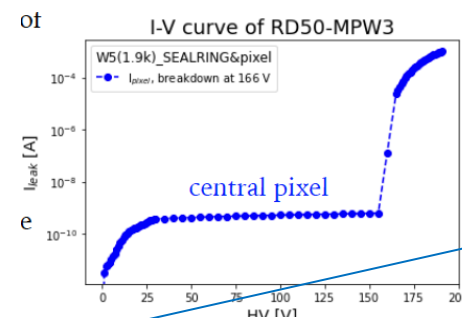
MPW2: small prototype

- pixels: $60 \times 60 \mu\text{m}^2$
- in-pix CSA + discriminator, analog R/O
- testbeams performed
- charge collection ok

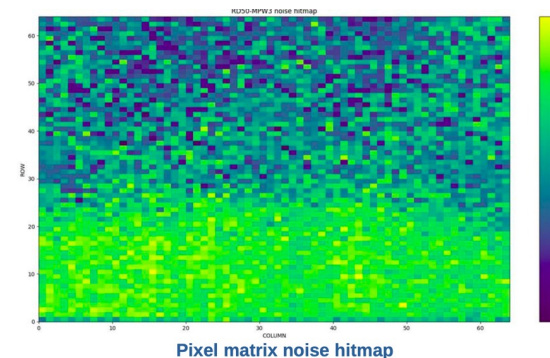
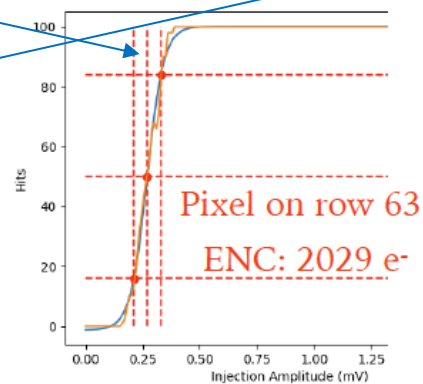


MPW3: added digital R/O (column drain)

- $V_{\text{breakdown}} \sim 150\text{V}$
- very high noise ($> 2000 e$) due to noise coupling from digital periphery
- Poor test beam efficiency due to high thresholds



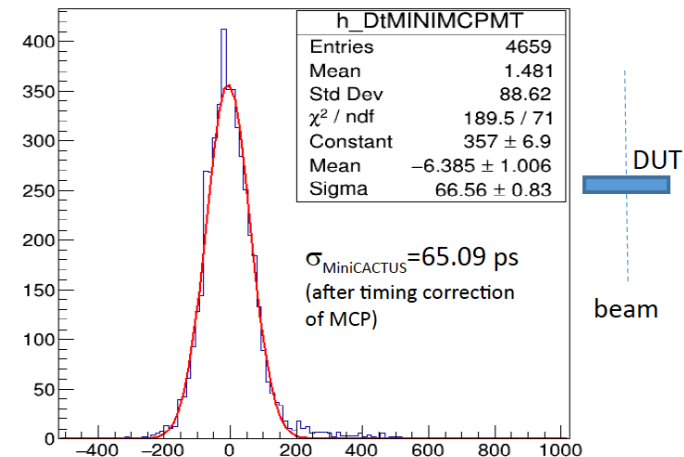
MPW4 (2024): backside processing to improve radiation hardness



Goal: Develop CMOS pixels for timing applications (~50 ps)

Mini CACTUS = small prototype to address limitations of CACTUS (low S/N)

- 65 ps mip time resolution achieved in testbeams
- compared calibrations and resolutions using photons of different energies (^{241}Am and @SOLEIL)
 - calibrations ✓
 - σ_t for photons (understandably) worse (320 ps)
- next:
 - characterisation after $1\text{e}14$, $1\text{e}15$, and $1\text{e}16$ $n_{\text{eq}}/\text{cm}^2$
 - new Mini-CACTUS submission May 2023



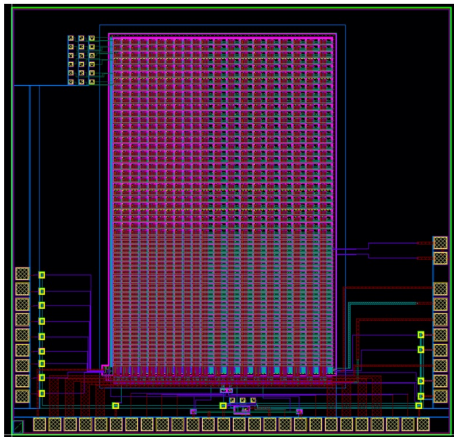
P. Schwemling, Y. Degerli et al

LFoundrxy 110 nm, TSI

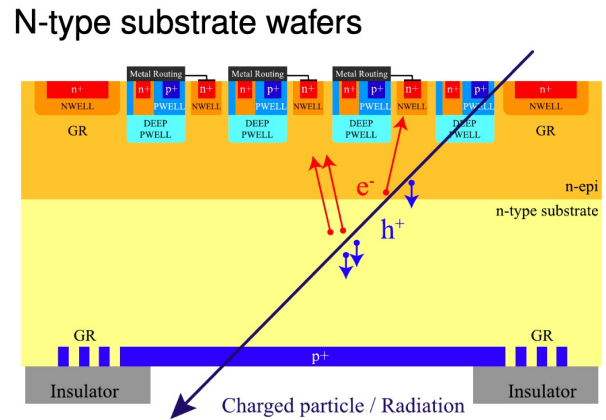
PSI developments

Goal: Generic R&D on DMAPS with TSI and technology platform in LF 110 nm provided by ARCADIA

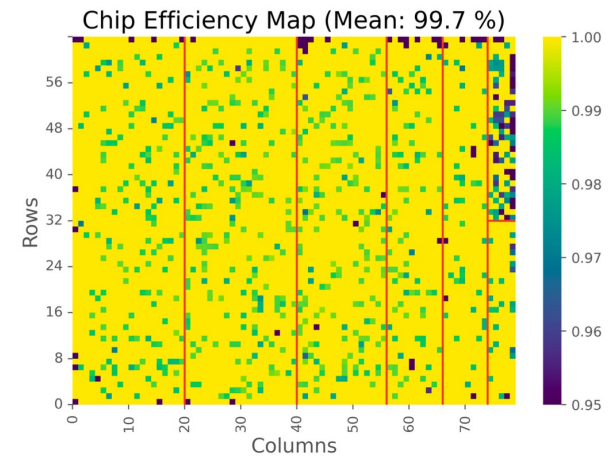
- 2 PSI TSI MAPS chips designed and manufactured with promising results, more test underway
- First LF 110 prototype designed and manufactured using the ARCADIA platform
- First results in test beam looks good → high efficiency (99,7%) and good spatial resolution (10 μm)
- Second version just arrived



2nd PSI TSI MAPS chip



Modified LF 110 nm process



TB results of 1st LF 110 chip

- Lots of activity at all fronts: *high granularity, radiation hardness and timing*
- Fabrication of devices completed in all lines
- First Milestones achieved (reports done or in process for review)
- All research lines are currently intensively characterizing their devices
- Many publications

BACK UP SLIDES

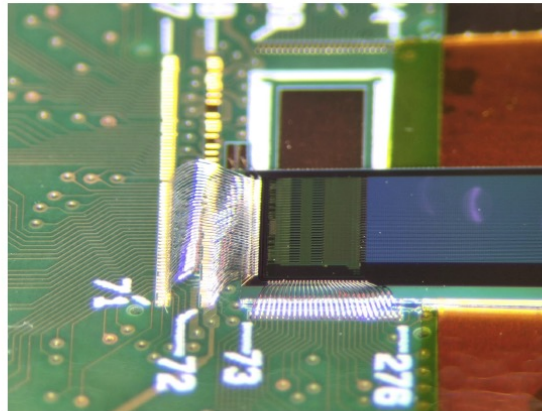
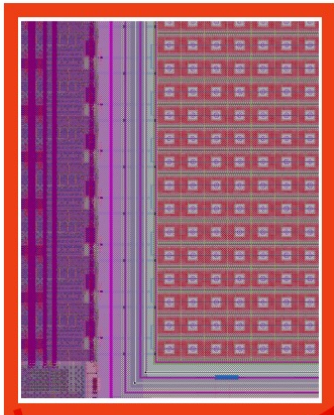
LFoondry 110 nm
ARCADIA

Goal: Develop DMAPS technology platform in 110 nm technology. Largely funded by INFN. Targeting small pixels, very low power, various thicknesses

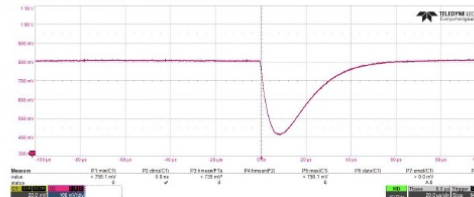
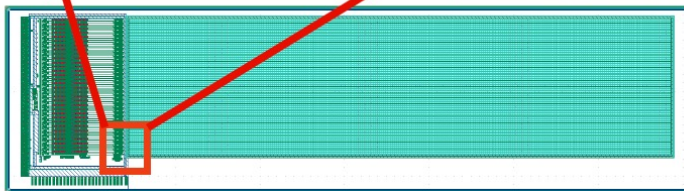
- MD1 main-demonstrator
- under test: Fully Depleted Monolithic Active Microstrip demonstrator -> looks good
- 27 wafers out from fab recently
- adding gain layer considered for LC3



Figure: CAD Layout of 32-block of 2x2566 50µm pixelised strips



Fully Depleted Monolithic Active Microstrip
Sensors: TCAD Simulation Study of an Innovative
Design Concept. Sensors 2021, 21, 1990.
<https://doi.org/10.3390/s21061990>



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- **Acknowledge AIDAInnova support of activities (where relevant)**
 - Articles, pre-prints, notes, slides at conferences... *proceedings of VCI2022!*
 - Official acknowledge text at AIDAInnova web site:
<https://aidainnova.web.cern.ch/publications>

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- Let us know of changes above.
- The AIDAinnova-WP5@cern.ch mailing list is used for general announcements and information.